

# 74LVC1G125

Bus buffer/line driver; 3-state

Rev. 11 — 2 July 2012

Product data sheet

## 1. General description

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The 74LVC1G125 provides one non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input ( $\overline{OE}$ ). A HIGH-level at pin  $\overline{OE}$  causes the output to assume a high-impedance OFF-state.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- CMOS low power consumption
- Inputs accept voltages up to 5 V
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Multiple package options
- Specified from  $-40$  °C to  $+85$  °C and  $-40$  °C to  $+125$  °C



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC1G125GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G125GV	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G125GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G125GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74LVC1G125GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74LVC1G125GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74LVC1G125GX	-40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

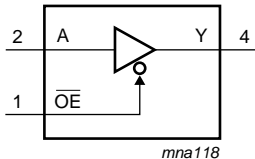

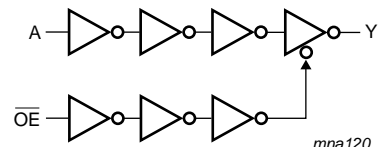
### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74LVC1G125GW	VM
74LVC1G125GV	V25
74LVC1G125GM	VM
74LVC1G125GF	VM
74LVC1G125GN	VM
74LVC1G125GS	VM
74LVC1G125GX	VM

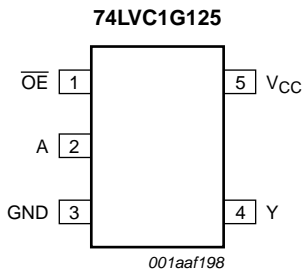
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

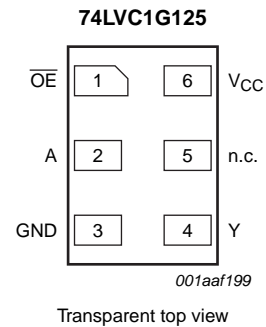
 <p><i>mna118</i></p>	 <p><i>mna119</i></p>	 <p><i>mna120</i></p>
<b>Fig 1. Logic symbol</b>	<b>Fig 2. IEC logic symbol</b>	<b>Fig 3. Logic diagram</b>

## 6. Pinning information

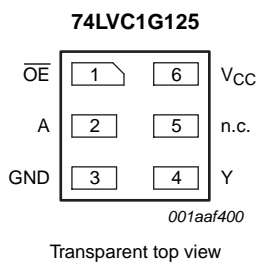
### 6.1 Pinning



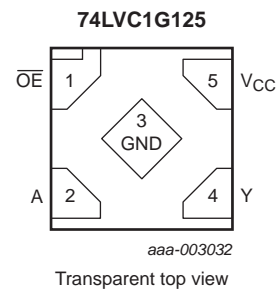
**Fig 4. Pin configuration SOT353-1 and SOT753**



**Fig 5. Pin configuration SOT886**



**Fig 6. Pin configuration SOT891, SOT1115 and SOT1202**



**Fig 7. Pin configuration SOT1226 (X2SON5)**

### 6.2 Pin description

**Table 3. Pin description**

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
$\overline{OE}$	1	1	output enable input
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
OE	A	Y
L	L	L
L	H	H
H	X	Z

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 X = don't care;  
 Z = high-impedance OFF-state.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		<sup>[1]</sup> -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
$V_O$	output voltage	Active mode	<sup>[1][2]</sup> -0.5	$V_{CC} + 0.5$	V
		Power-down mode	<sup>[1][2]</sup> -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±50	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	<sup>[3]</sup> -	250	mW
$T_{stg}$	storage temperature		-65	+150	°C

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 [2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.  
 [3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
 For XSON6 and X2SON5 package: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	$V_{CC}$	V
		$V_{CC} = 0$ V; Power-down mode	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	-	-	20	ns/V
		$V_{CC} = 2.7$ V to 5.5 V	-	-	10	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
<b><math>T_{amb} = -40</math> °C to +85 °C</b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	V
		$V_{CC} = 4.5$ V to 5.5 V	$0.7 \times V_{CC}$	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	V
		$V_{CC} = 4.5$ V to 5.5 V	-	-	$0.3 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65$ V to 5.5 V; $I_O = 100$ $\mu$ A	-	-	0.1	V
		$V_{CC} = 1.65$ V; $I_O = 4$ mA	-	-	0.45	V
		$V_{CC} = 2.3$ V; $I_O = 8$ mA	-	-	0.3	V
		$V_{CC} = 2.7$ V; $I_O = 12$ mA	-	-	0.4	V
		$V_{CC} = 3.0$ V; $I_O = 24$ mA	-	-	0.55	V
		$V_{CC} = 4.5$ V; $I_O = 32$ mA	-	-	0.55	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65$ V to 5.5 V; $I_O = -100$ $\mu$ A	$V_{CC} - 0.1$	-	-	V
		$V_{CC} = 1.65$ V; $I_O = -4$ mA	1.2	-	-	V
		$V_{CC} = 2.3$ V; $I_O = -8$ mA	1.9	-	-	V
		$V_{CC} = 2.7$ V; $I_O = -12$ mA	2.2	-	-	V
		$V_{CC} = 3.0$ V; $I_O = -24$ mA	2.3	-	-	V
		$V_{CC} = 4.5$ V; $I_O = -32$ mA	3.8	-	-	V
$I_I$	input leakage current	$V_{CC} = 0$ V to 5.5 V; $V_I = 5.5$ V or GND	-	$\pm 0.1$	$\pm 5$	$\mu$ A
$I_{OZ}$	OFF-state output current	$V_{CC} = 3.6$ V; $V_I = V_{IH}$ or $V_{IL}$ ; $V_O = 5.5$ V or GND	-	$\pm 0.1$	$\pm 10$	$\mu$ A

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$I_{OFF}$	power-off leakage current	$V_{CC} = 0\text{ V}; V_I \text{ or } V_O = 5.5\text{ V}$	-	$\pm 0.1$	$\pm 10$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = 5.5\text{ V or GND}; V_{CC} = 1.65\text{ V to } 5.5\text{ V}; I_O = 0\text{ A}$	-	0.1	10	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per pin; $V_{CC} = 2.3\text{ V to } 5.5\text{ V}; V_I = V_{CC} - 0.6\text{ V}; I_O = 0\text{ A}$	-	5	500	$\mu\text{A}$
$C_I$	input capacitance		-	5	-	pF
<b><math>T_{amb} = -40\text{ }^\circ\text{C to } +125\text{ }^\circ\text{C}</math></b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65\text{ V to } 1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V to } 3.6\text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$	$0.7 \times V_{CC}$	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65\text{ V to } 1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7\text{ V to } 3.6\text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$	-	-	$0.3 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$V_{CC} = 1.65\text{ V to } 5.5\text{ V}; I_O = 100\text{ }\mu\text{A}$	-	-	0.1	V
		$V_{CC} = 1.65\text{ V}; I_O = 4\text{ mA}$	-	-	0.70	V
		$V_{CC} = 2.3\text{ V}; I_O = 8\text{ mA}$	-	-	0.45	V
		$V_{CC} = 2.7\text{ V}; I_O = 12\text{ mA}$	-	-	0.60	V
		$V_{CC} = 3.0\text{ V}; I_O = 24\text{ mA}$	-	-	0.80	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$				
		$V_{CC} = 1.65\text{ V to } 5.5\text{ V}; I_O = -100\text{ }\mu\text{A}$	$V_{CC} - 0.1$	-	-	V
		$V_{CC} = 1.65\text{ V}; I_O = -4\text{ mA}$	0.95	-	-	V
		$V_{CC} = 2.3\text{ V}; I_O = -8\text{ mA}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V}; I_O = -12\text{ mA}$	1.9	-	-	V
		$V_{CC} = 3.0\text{ V}; I_O = -24\text{ mA}$	2.0	-	-	V
$I_I$	input leakage current	$V_{CC} = 0\text{ V to } 5.5\text{ V}; V_I = 5.5\text{ V or GND}$	-	-	$\pm 100$	$\mu\text{A}$
		$V_{CC} = 3.6\text{ V}; V_I = V_{IH} \text{ or } V_{IL}; V_O = 5.5\text{ V or GND}$	-	-	$\pm 200$	$\mu\text{A}$
		$V_{CC} = 0\text{ V}; V_I \text{ or } V_O = 5.5\text{ V}$	-	-	$\pm 200$	$\mu\text{A}$
		$V_I = 5.5\text{ V or GND}; V_{CC} = 1.65\text{ V to } 5.5\text{ V}; I_O = 0\text{ A}$	-	-	200	$\mu\text{A}$
		per pin; $V_{CC} = 2.3\text{ V to } 5.5\text{ V}; V_I = V_{CC} - 0.6\text{ V}; I_O = 0\text{ A}$	-	-	5000	$\mu\text{A}$

[1] All typical values are measured at  $V_{CC} = 3.3\text{ V}$  and  $T_{amb} = 25\text{ }^\circ\text{C}$ .

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	A to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	3.3	8.0	1.0	10.5	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.2	5.5	0.5	7	ns
		V <sub>CC</sub> = 2.7 V	0.5	2.5	5.5	0.5	7	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	2.1	4.5	0.5	6	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.5	1.7	4.0	0.5	5.5	ns
t <sub>en</sub>	enable time	OE to Y; see <a href="#">Figure 9</a> <sup>[3]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.1	9.4	1.0	12	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.8	6.6	0.5	8.5	ns
		V <sub>CC</sub> = 2.7 V	0.5	3.3	6.6	0.5	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	2.4	5.3	0.5	7	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.5	2.1	5.0	0.5	6.5	ns
t <sub>dis</sub>	disable time	OE to Y; see <a href="#">Figure 9</a> <sup>[4]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.3	9.2	1.0	12	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.7	5.0	0.5	6.5	ns
		V <sub>CC</sub> = 2.7 V	0.5	3.0	5.0	0.5	6.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	3.1	5.0	0.5	6.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.5	2.2	4.2	0.5	5.5	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[5]</sup>						
		output enabled	-	25	-	-	-	pF
		output disabled	-	6	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>

[3] t<sub>en</sub> is the same as t<sub>PZH</sub> and t<sub>PZL</sub>

[4] t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>

[5] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

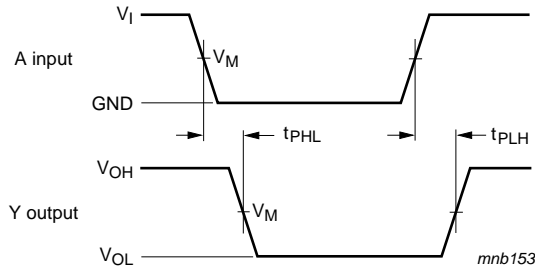
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

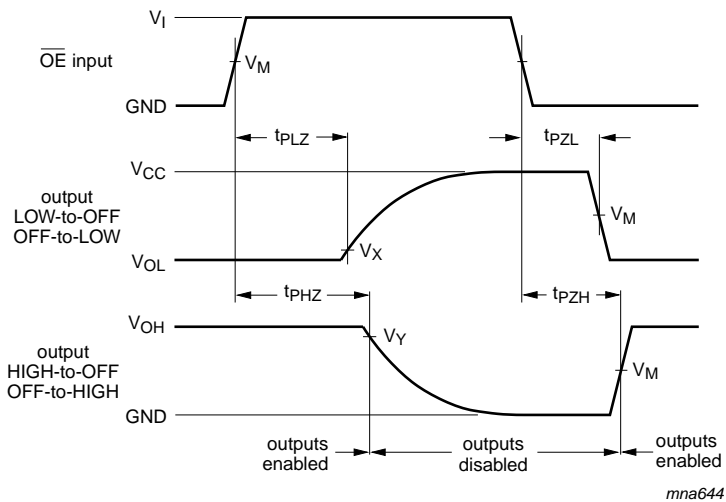
∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

12. Waveforms



Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. Input A to output Y propagation delay times**



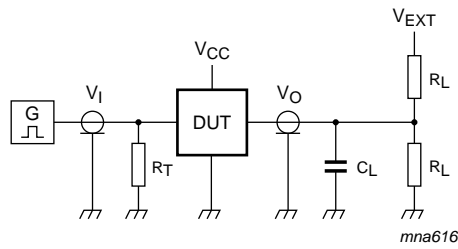
Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 9. 3-state enable and disable times**

**Table 9. Measurement points**

Supply voltage	Input	Output		
$V_{CC}$	$V_M$	$V_M$	$V_X$	$V_Y$
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15 V$	$V_{OH} - 0.15 V$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15 V$	$V_{OH} - 0.15 V$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$





Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 10. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Input		Load		$V_{EXT}$		
$V_{CC}$	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	1 k $\Omega$	open	GND	$2V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	500 $\Omega$	open	GND	$2V_{CC}$
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	6 V
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	6 V
4.5 V to 5.5 V	$V_{CC}$	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	$2V_{CC}$

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

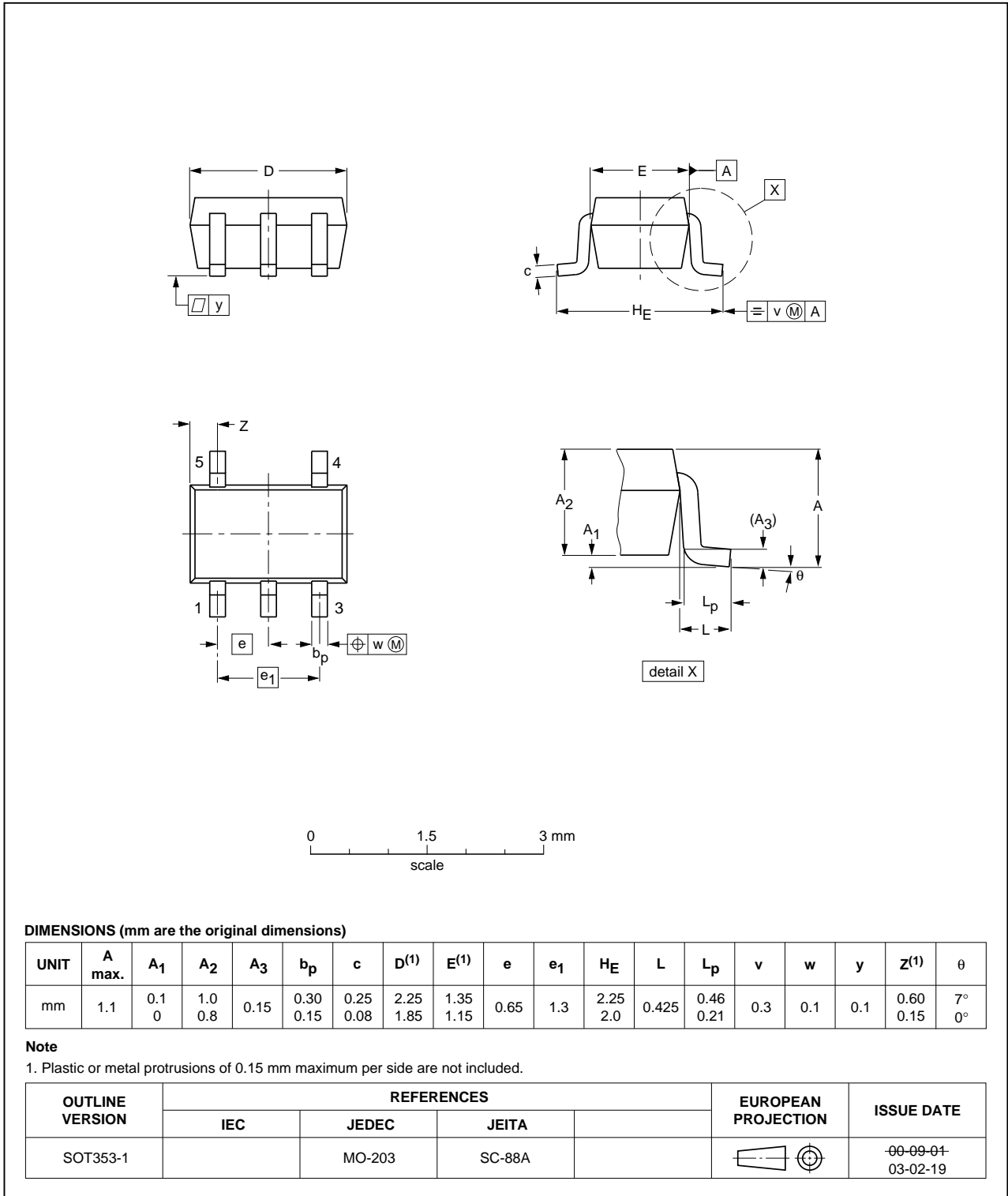


Fig 11. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

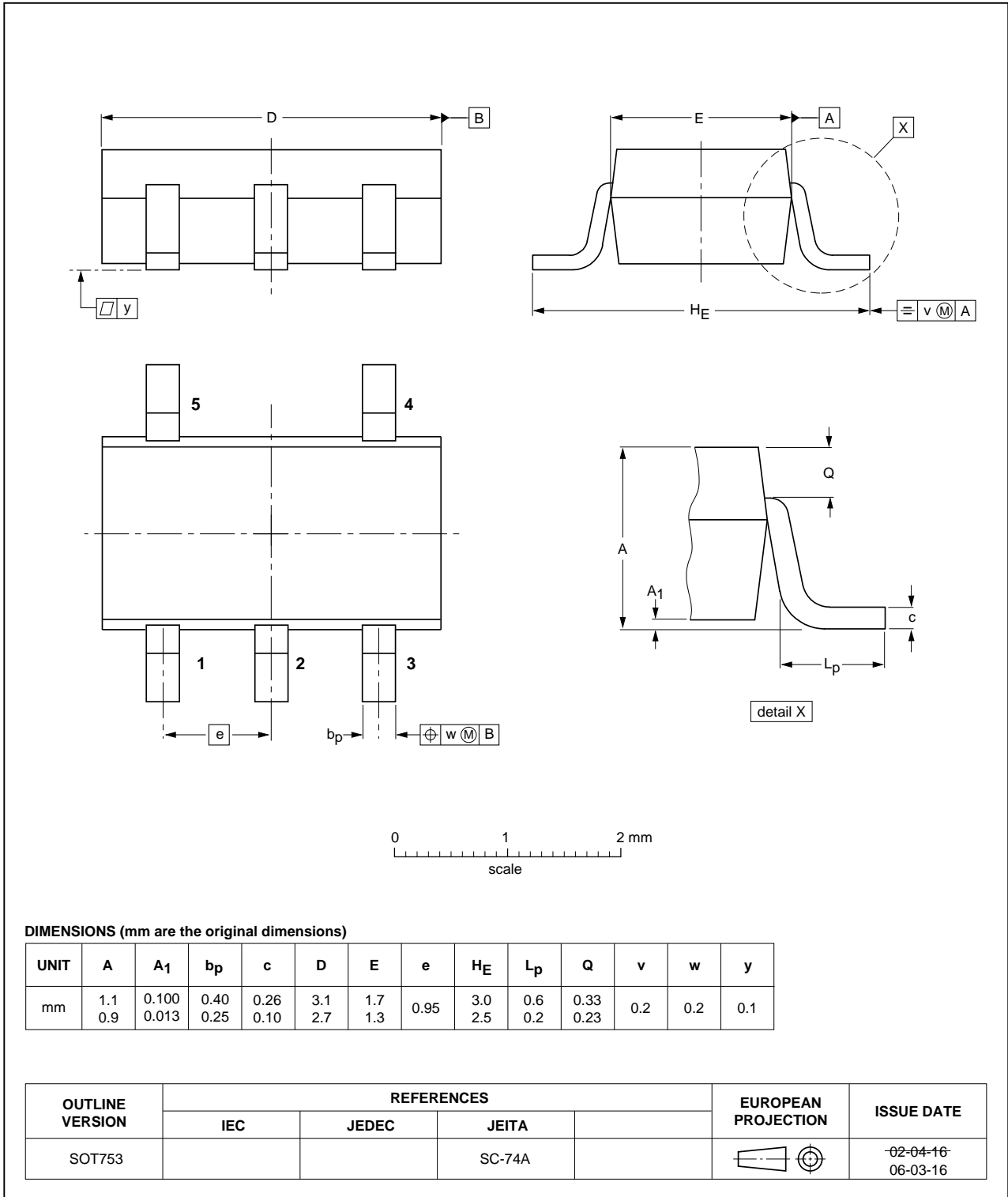


Fig 12. Package outline SOT753

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

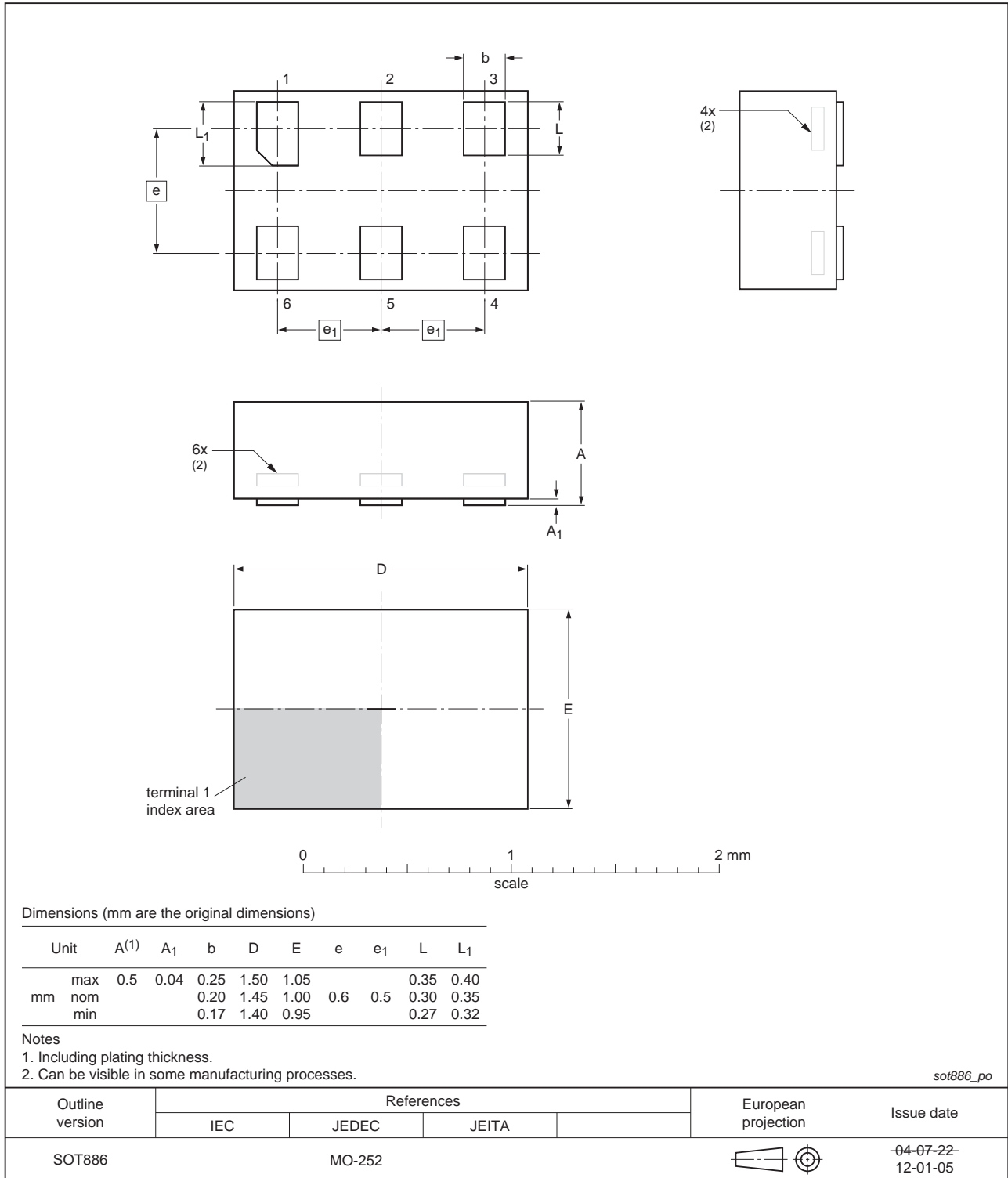


Fig 13. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891



Fig 14. Package outline SOT891 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

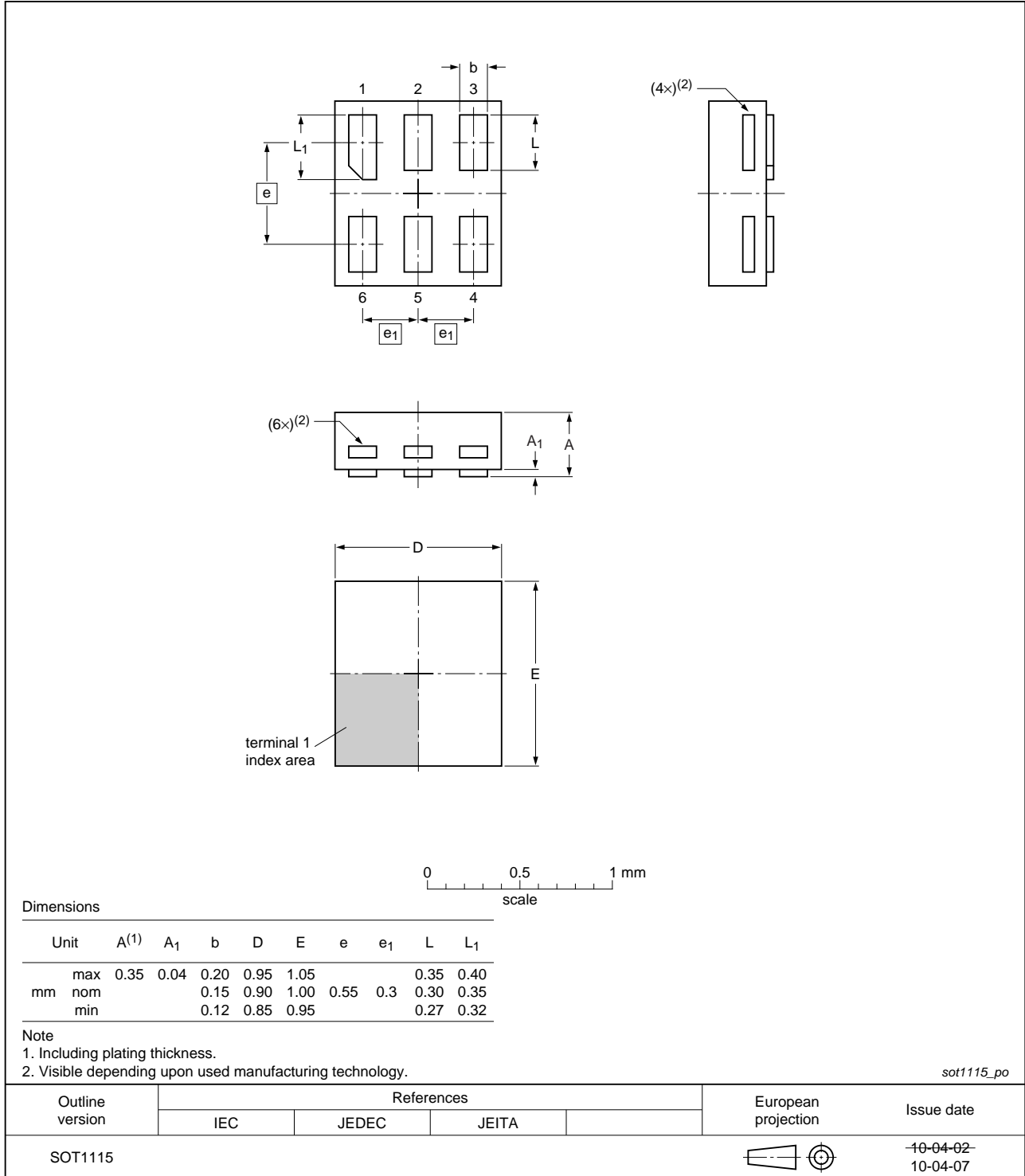


Fig 15. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;**  
**6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

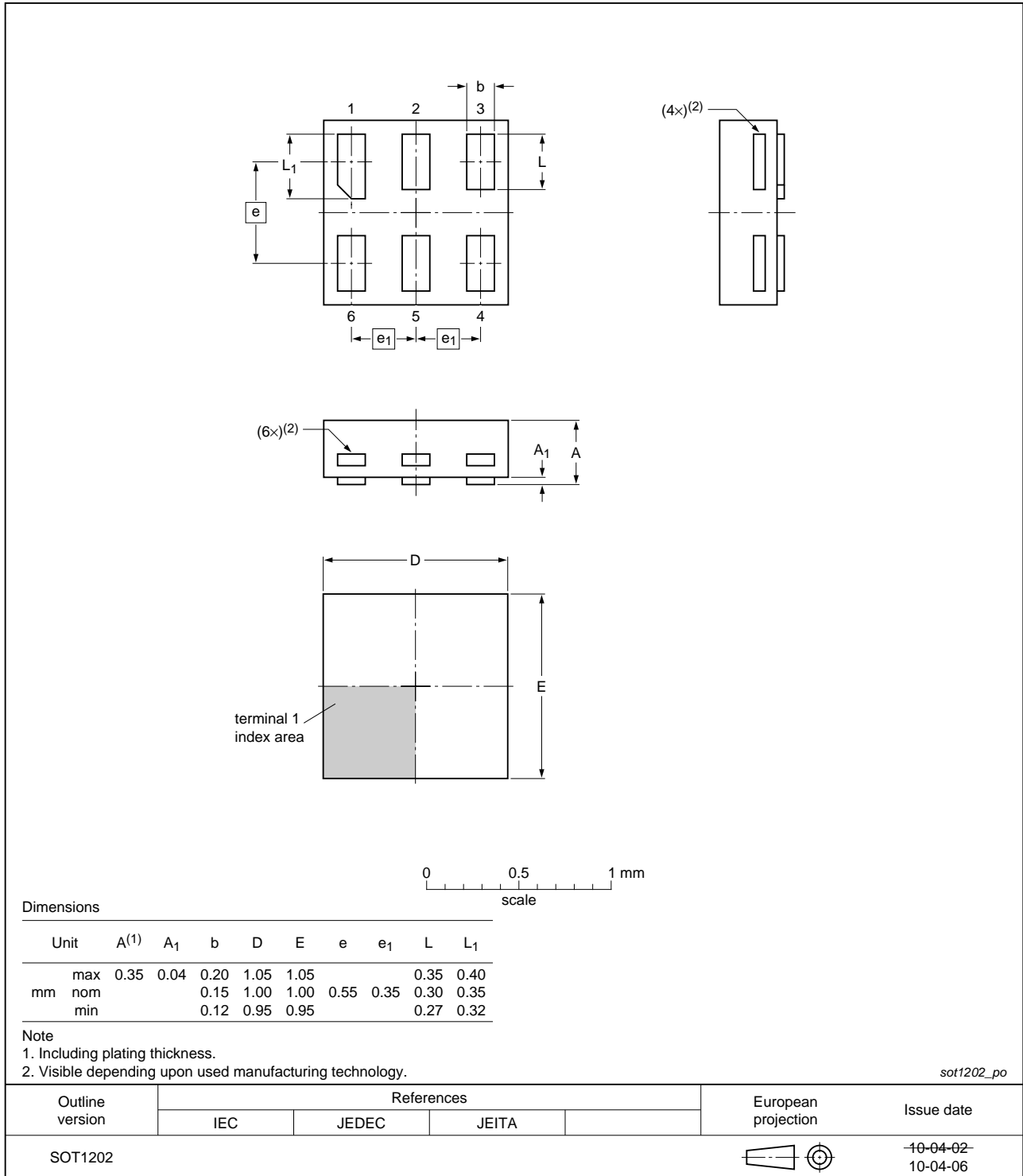


Fig 16. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

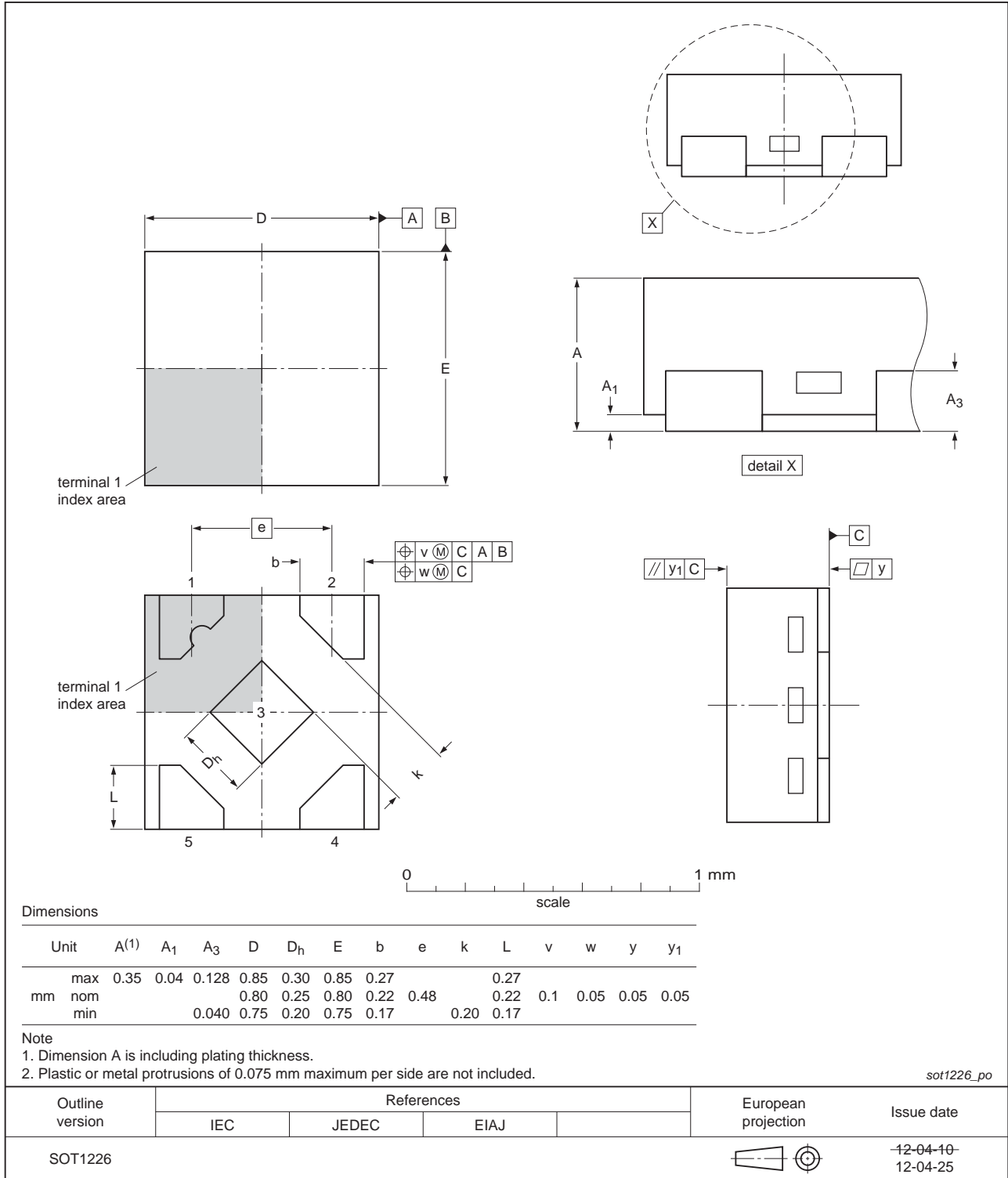


Fig 17. Package outline SOT1226 (X2SON5)



## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G125 v.11	20120702	Product data sheet	-	74LVC1G125 v.10
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74LVC1G125GX (SOT1226)</li> <li>Package outline drawing of SOT886 (<a href="#">Figure 13</a>) modified.</li> </ul>			
74LVC1G125 v.10	20111207	Product data sheet	-	74LVC1G125 v.9
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74LVC1G125 v.9	20101229	Product data sheet	-	74LVC1G125 v.8
74LVC1G125 v.8	20100824	Product data sheet	-	74LVC1G125 v.7
74LVC1G125 v.7	20070830	Product data sheet	-	74LVC1G125 v.6
74LVC1G125 v.6	20060912	Product data sheet	-	74LVC1G125 v.5
74LVC1G125 v.5	20040915	Product specification	-	74LVC1G125 v.4
74LVC1G125 v.4	20021118	Product specification	-	74LVC1G125 v.3
74LVC1G125 v.3	20020528	Product specification	-	74LVC1G125 v.2
74LVC1G125 v.2	20010406	Product specification	-	74LVC1G125 v.1
74LVC1G125 v.1	20001222	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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